A Successful 2015 Pan Pacific Symposium

The 2015 Pan Pacific Microelectronics Symposium, held 2-5 February at the Sheraton Kauai, highlighted more than 50 papers from 14 countries.

The Iwao Tachikawa Best Paper Award went to Peter Borgesen, Ph.D., Binghamton University for his paper “Intermetallic Issues and Challenges in 2.5/3 D Assembly Micro-Joints.” Available in the SMTA Bookstore, the 2015 Pan Pacific Proceedings feature the technical papers from all sessions.

Here’s to 20 Years

“2015 marked the 20th anniversary of the Pan Pacific Microelectronics Symposium, one of the longest running events sponsored by the SMTA,” noted steering committee chair Charles E. Bauer, Ph.D., TechLead Corporation. The 20th Anniversary celebration included a special reception and a slideshow presentation commemorating the symposium’s long standing history.

MARK YOUR CALENDAR!

PanPac 2016
Jan 25-28
Hapuna Beach Prince Hotel
Big Island, Hawaii

The uniqueness of the Pan Pac lies in the high quality attendees and exceptional presentations it draws as well as the casual and social atmosphere that builds long term relationships.

- David Raby, President
STI Electronics

2016 CALL FOR PAPERS

Deadline: 15 June 2015
Submit Your Abstract

The tremendous value contributed by the Pan Pacific lies in the sharing of global information and perspectives, discussions and debates leading to in depth understanding of technologies and trends impacting the electronics industry, and foundational relationships with and among industry thought leaders. The Pan Pacific builds relationships founded on familiarity and trust engendered by the intimacy of a small conference (<150 people) in a location isolated from the marketing pressures of a major trade show and/or proximity to a central industry location. Leaders from around the world, representing more than 30 countries over the past 20 years, pursue extended discussions and even business or technical debates rather than simply exchanging business cards and moving on to another booth! Many significant events spun out of the Pan Pacific where new technologies as well as manufacturing and business trends often find their earliest exposure, not to mention first thorough exploration and critique by global thought leaders! Events such as the International Wafer Level Packaging Conference, the Symposium on Counterfeit Parts & Materials, the European 3D TSV Summit and the upcoming LED Assembly, Reliability & Test Symposium trace their roots to special sessions/tracks at the Pan Pacific.

Attending Pan Pac for the past 19 years gave me a chance to meet and network with senior level industry executives and experts from around the world.

-Rod Howell, CEO
Libra Industries

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My experience at Pan Pac rewards me with very stimulating sessions and provides a global outlook on activities across the world. I look forward to another great experience in 2016!

-Terry Bowen, Fellow
TE Connectivity